Unassigned design blocks	15-Nov-19	2019				2020				2021			
Item description	Sub-item	Q1 2019	Q2 2019	Q3 2019	Q4 2019	Q1 2020	Q2 2020	Q3 2020	Q4 2020	Q1 2021	Q2 2021	Q3 2021	Q4 2021
Documentation	System requirements Conceptual design/architecture FEB spec./architecture Photosensor connectivity spec. Backplane spec. OCC spec. Synchronisation spec. Power supply spec. Calibration system spec.				1st	1st 1st	1st					1	
	DAQ spec.						1st						
Front End Board	DC/DC conv. EMI testing [0.2 T] FEB v1 Firmware development FEB v2 DAQ adapter [OCCv0 for FEB tests]					FEB 0.2T FEB v1 D P-o+pwr est.	esign	Prod. Firmware v1 Prod.	Tests	Design	Firmwa Prod.	re v2 Q.A.	]
Photosensor connectivity	MPPC PCB [v2]					MPPC PCB des	sign		Prod.				
	Cable assembly and routing		Routi	ng concept				Cable assembly	/ prod.				
	Patch panel					Design & prot	0		Prod.				
Backplane	FEB-to-OCC link					FEB-to-OCC lir	<u>U</u>		Prod.				
	Low Voltage distribution [24V]					L.V. dis	tri. design		Prod.				
Power supplies (0 T)	Power modules [out of rack]						P.S. de	sign+proto.	Proc	ł. 🛛			
Synchronisation system	Master Clock Board					MCB de	sign+proto			Prod.			
	Clock/sync distribution (fanout)					Fanout design	+proto			Prod.			
Optical Concentrator Card									ind proto.			Prod.	
	Slow control link							Design a	nd proto.			Prod.	
DAQ	DAQ system	DAQ system design							Proc	ł.			
Calibration system	LED driver					LED driver des	ign			Prod.			
	Optical system (scint. block)				Optical design	l				Prod.			
Electronics mechanics	FEB crates and support mechanics				Crates design			Prod.		_			
	Patch panel/backplane mechanics					anel design		_	Prod.				
	Various modules (MCR, PW, DAQ)				MCR	<mark>, PW, DAQ meca</mark>			Prod.		_		
	Miscellaneous cabling					General cablir	-			Prod.			
	Cooling system					FEB cooling sy	stem			Prod.			
Integration	Reference readout chain									Reference	readout chain	•	
	Surface assembly and tests J-PARC										Surface	」	
	Pit installation												Pit